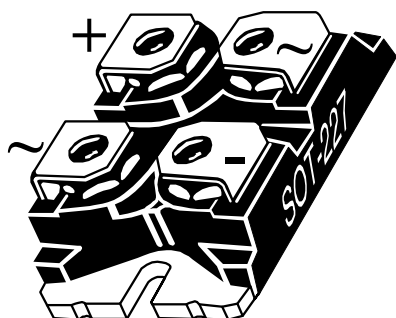
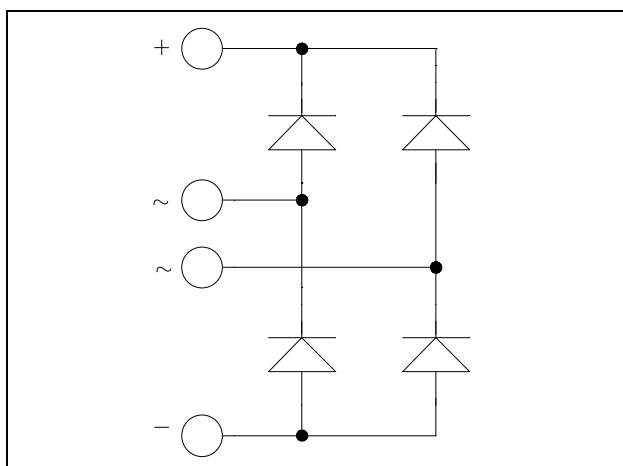


ISOTOP® Fast Diode Full Bridge Power Module

$V_{RRM} = 600V$
 $I_F = 75A @ T_c = 80^\circ C$



Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP® Package (SOT-227)

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit
V _R	Maximum DC reverse Voltage			600	V
V _{RRM}	Maximum Peak Repetitive Reverse Voltage				
I _{F(AV)}	Maximum Average Forward Current	Duty cycle = 50%	T _C = 80°C	75	A
I _{FRM}	Maximum repetitive forward current limited by T _{Imax}	8.3ms	T _J = 45°C	150	



CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V _F	Diode Forward Voltage	I _F = 75A	T _j = 25°C		1.6	2	V
			T _j = 150°C		1.5		
I _{RM}	Maximum Reverse Leakage Current	V _R = 600V	T _j = 25°C			250	μA
			T _j = 150°C			500	

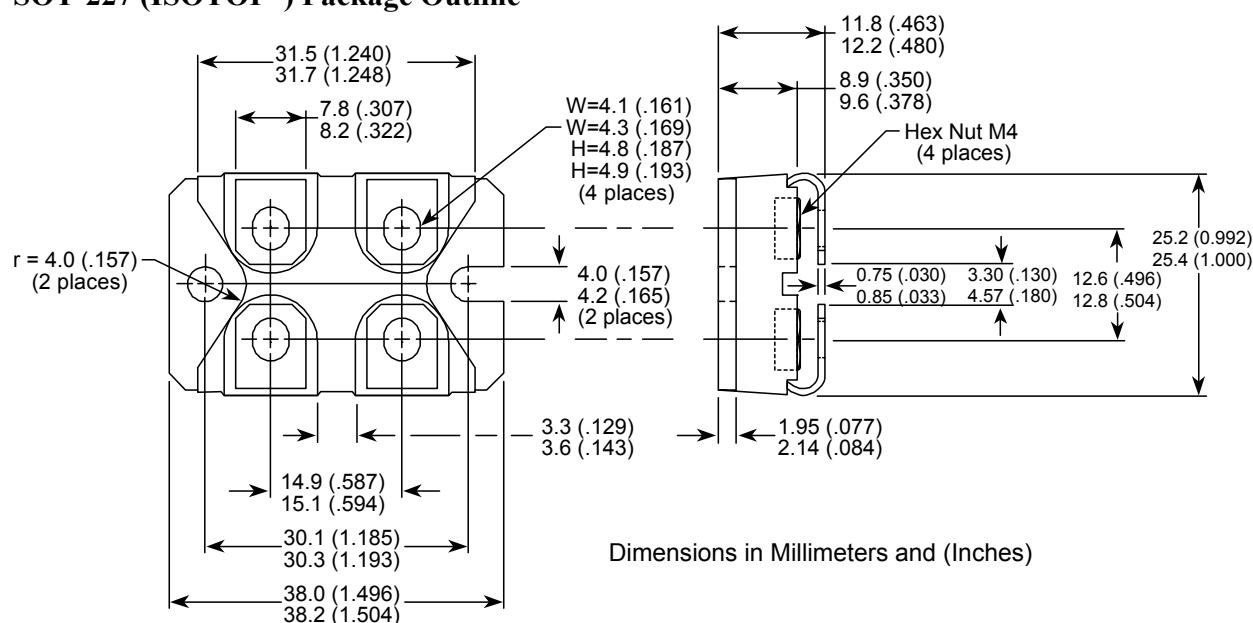
Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time	I _F = 75A V _R = 300V di/dt = 2000A/μs	T _j = 25°C		100		ns
			T _j = 150°C		150		
Q _{rr}	Reverse Recovery Charge		T _j = 25°C		3.6		μC
			T _j = 150°C		7.6		
E _{rr}	Reverse Recovery Energy		T _j = 25°C		0.85		mJ
			T _j = 150°C		1.8		

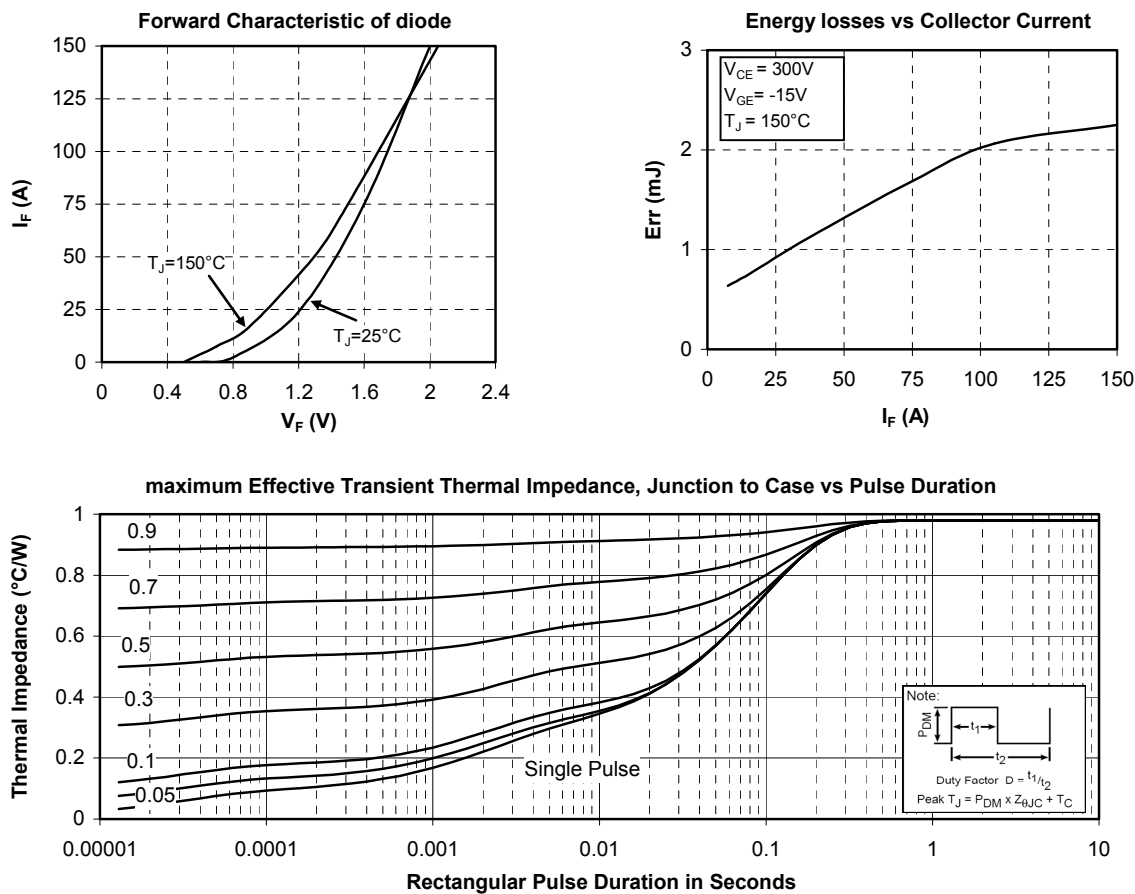
Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal resistance			0.98	$^\circ\text{C}/\text{W}$
R_{thJA}	Junction to Ambient			20	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, 50/60Hz	2500			V
T_j, T_{STG}	Storage Temperature Range	-55		175	$^\circ\text{C}$
T_L	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

SOT-227 (ISOTOP[®]) Package Outline



Typical Performance Curve



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